

BAV70

Rev.F Aug.-2020

描述 / Descriptions

SOT-23 塑封封装 硅半导体二极管。Silicon Diode in a SOT-23 Plastic Package .

特征 / Features

小信号二极管，无卤产品。

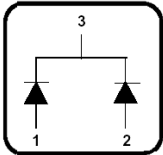
Small signal diode, HF Product.

用途 / Applications

高导电率的超快速二极管。

High Conductance Ultra Fast Diode.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN: See Equivalent Circuit.

放大及印章代码 / h_{FE} Classifications & Marking

Marking	HA4
---------	-----

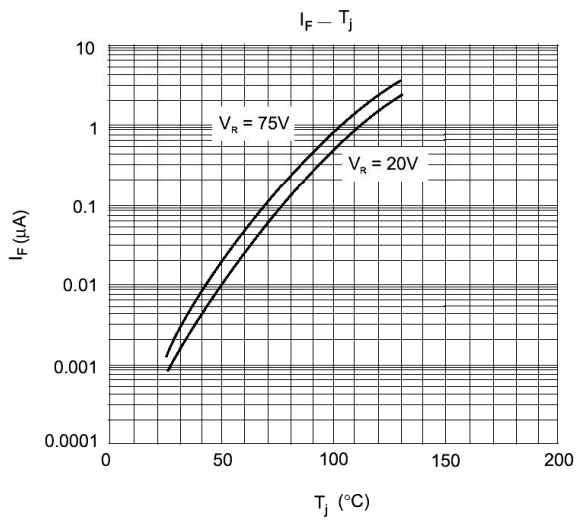
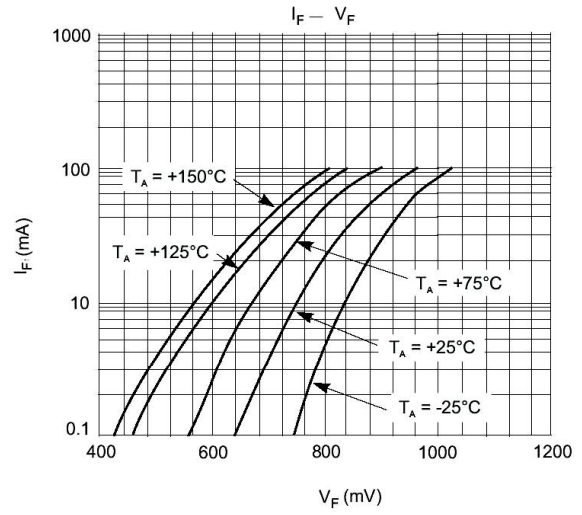
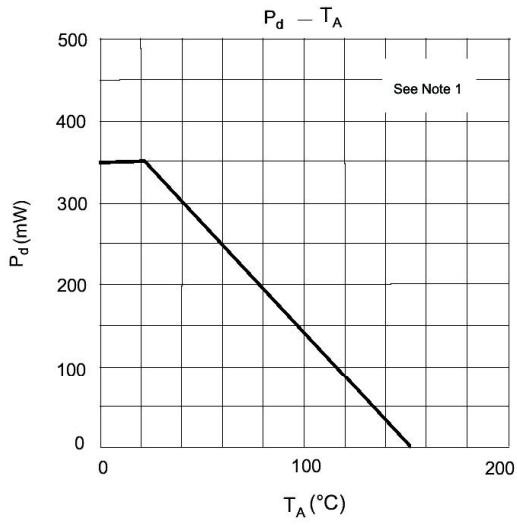
极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Maximum Repetitive Reverse Voltage	V_{RRM}	75	V
Breakdown Voltage	V_R	70	V
Average Rectified Forward Current	$I_{F(AV)}$	200	mA
Non-repetitive Peak Forward Surge Current	$I_{FSM(1)}$ (pulse width=1.0S)	1.0	A
	$I_{FSM(2)}$ (pulse width=1.0mS)	2.0	A
Power Dissipation	P_D	350	mW
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	357	°C/W
Junction Temperature	T_j	150	°C
Storage Temperature Range	T_{stg}	-55~150	°C

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Breakdown Voltage	V_R	$I_R=100\mu A$	70			V
Forward Voltage	V_F	$I_F=1.0mA$			715	mV
		$I_F=10mA$			855	mV
		$I_F=50mA$			1.0	V
		$I_F=150mA$			1.25	V
Instantaneous Reverse Current	I_R	$V_R=70V$			5.0	μA
		$V_R=25V$ $T_A=150^\circ C$			60	μA
		$V_R=70V$ $T_A=150^\circ C$			100	μA
Total Capacitance	C_T	$V_R=0$ $f=1.0MHz$			1.5	pF
Reverse Recovery Time	t_{rr}	$I_F=1R=10mA$ $I_{RR}=1.0mA$ $R_L=100\Omega$			6.0	ns

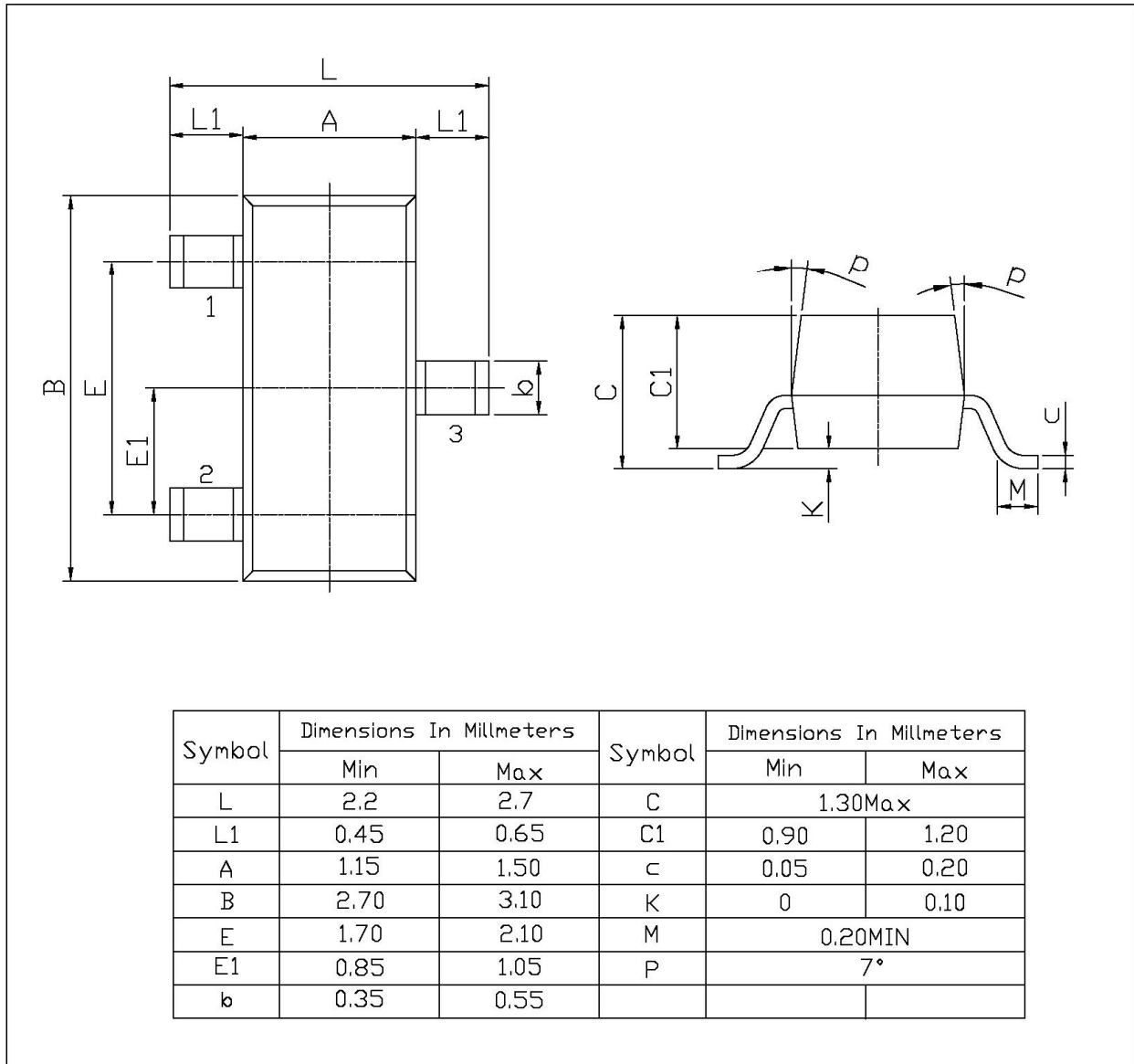
电参数曲线图 / Electrical Characteristic Curve



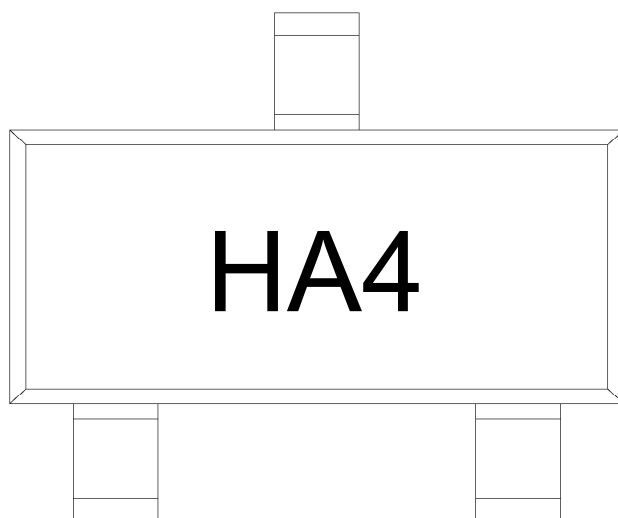
外形尺寸图 / Package Dimensions

SOT-23

单位: mm



印章说明 / Marking Instructions



说明：

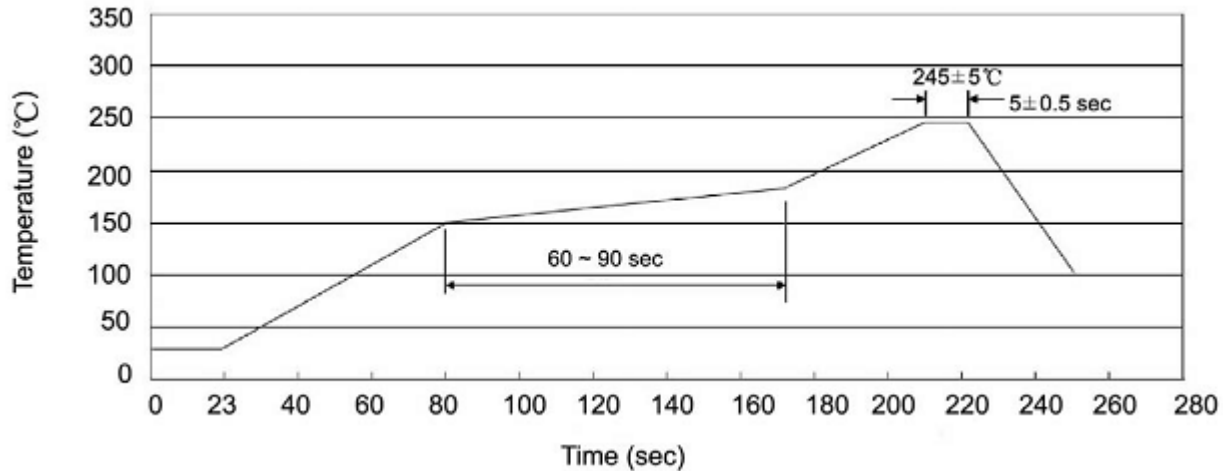
H： 为公司代码

A4： 为型号代码

Note:

H: Company Code.

A4: Product Type Code.

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)


说明：

- 1、预热温度 25~150°C，时间 60~90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	6	180,000	7" ×8	180×120×180	390×385×205

使用说明 / Notices